AMENDMENTS TO THE CLAIMS:

Please replace the claims with the claims provided in the listing below wherein status, amendments, additions and cancellations are indicated.

- 1. (Currently amended) A tungsten-based sintered body consisting of at least either one selected from the group consisting of tungsten, doped tungsten, a tungsten-based material and a tungsten-molybdenum alloy, wherein said doped tungsten consists of comprises tungsten doped with 100 ppm or less (except for zero ppm) of alkali metal, and said tungsten-based material consists of comprises tungsten containing 4 weight% or less (except for zero weight%) of at least one additive selected from the group consisting of oxides of cerium, thorium, lanthanum, yttrium, strontium, calcium, zirconium and hafnium, wherein said tungsten-based sintered body has an isotropic crystal structure, a relative density of 99.5% or more, and an average crystal grain size of 30 μm or less.
- 2. (Original) The tungsten-based sintered body as defined in claim 1, which includes pores each having a major axis of 1 μ m or more, wherein the number of the pores is 10000 or less per 1 mm² of unit cross-sectional area thereof.

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Docket No. F-9173

- 3. (Original) The tungsten-based sintered body as defined in claim 1 or 2, which has a hardness difference of 1.0 or less in terms of HRA between a surface portion and an inside portion thereof.
- 4. (Currently amended) The tungsten-based sintered body as defined in either one of claims 1 to 3 claim 1 or 2, which has a recrystallization temperature of at least 1600°C or more.
- 5. (Currently amended) The tungsten-based sintered body as defined in either one of claims 1 to 4 claim 1 or 2, which has a ratio of a minimum value to a maximum value of an electric resistivity of 1.1 or less between any two points therein.
- 6. (Currently amended) The tungsten-based sintered body as defined in either one of claims 1 to 5 claim 1 or 2, which has a ratio of a minimum value to a maximum value of a thermal conductivity of 1.1 or less between any two points therein.
- 7. (Currently amended) A discharge lamp electrode formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.

- 8. (Currently amended) A sputtering target formed of the tungstenbased sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 9. (Currently amended) A crucible formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 10. (Currently amended) A radiation shielding member formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 11. (Currently amended) A resistance welding electrode formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 12. (Currently amended) A semiconductor element mounting substrate formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 13. (Currently amended) A structural member formed of the tungstenbased sintered body as defined in either one of claims 1 to 6 claim 1 or 2.

- 14. (Currently amended) A switch contact formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 15. (Currently amended) A member for semiconductor manufacturing equipment, which is formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 16. (Currently amended) A member for an ion-implantation apparatus, which is formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 17. (Currently amended) An internal member for a nuclear fusion reactor, which is formed of the tungsten-based sintered body as defined in either one of claims 1 to 6 claim 1 or 2.
- 18. (Currently amended) A method for producing a tungsten-based sintered body, comprising:

subjecting a raw powder having an average particle size of 0.5 to 4 μm to a CIP process at a pressure of 350 MPa or more to form a powder compact, wherein said raw material consists of at least either one selected from the group

consisting of: tungsten; doped tungsten consisting of comprising tungsten doped with 100 ppm or less of alkali metal; a material consisting of comprising tungsten containing up to 4 weight% of at least one additive selected from the group consisting of oxides of cerium, thorium, lanthanum, yttrium, strontium, calcium, zirconium and hafnium; and a tungsten-molybdenum alloy;

sintering said powder compact in a hydrogen gas atmosphere at a sintering temperature of 1600°C or more for a holding time of 5 hours or more to form a sintered compact; and

subjecting said sintered compact to a HIP process in an argon gas atmosphere under conditions of 150 MPa or more and 1900°C or more.